



Commission launches Chips Joint Undertaking under the European Chips Act

Brussels, 30 November 2023

Today the Commission has officially inaugurated the [Chips Joint Undertaking \(Chips JU\)](#), which will reinforce the European semiconductor ecosystem and Europe's technological leadership. It will bridge the gap between research, innovation and production thereby facilitating the commercialisation of innovative ideas. The Chips JU will, among others, deploy pilot lines for which the Commission announced today the first call with **€1.67 billion** of EU funding. This is expected to be matched by funds from Member States to reach **€3.3 billion**, plus additional private funds.

In addition, the **European Semiconductor Board** held its first meeting today. The Board brings together Member States to provide advice to the Commission on the consistent implementation of the [European Chips Act](#) and on international collaboration in semiconductors. It will be the key platform for coordination between the Commission, Member States, and stakeholders to address issues relating to the resilience of the supply chain and possible crisis responses.

The Chips Joint Undertaking

The Chips JU is the main implementer of the [Chips for Europe Initiative](#) (expected total budget €15.8 billion until 2030). The Chips JU aims at strengthening Europe's semiconductor ecosystem and economic security by managing an expected budget of nearly €11 billion by 2030, provided by the EU and participating states.

The Chips JU will:

- Set up pre-commercial, innovative pilot lines, providing industry state-of-the-art facilities to test, experiment and validate semiconductor technologies and system design concepts;
- Deploy a cloud-based Design Platform for design companies across the EU;
- Support the development of advanced technology and engineering capacities for quantum chips;
- Establish a network of competence centres and promote skills development.

The work of the Chips JU reinforces Europe's technological leadership by facilitating the transfer of knowledge from the lab to the fab, bridging the gap between research, innovation and industrial activities, and by promoting the commercialisation of innovative technologies by European industry including start-ups and SMEs.

First calls for funding Chips pilot lines

To launch its first calls for innovative pilot lines, the Chips JU will make **€1.67 billion in EU funding** available. The calls are open to organisations that wish to establish pilot lines in Member States, typically research and technology organisations, calling for proposals on:

- **Fully Depleted Silicon on Insulator, towards 7 nm:** This transistor architecture is a European innovation and has distinct advantages for high-speed and energy-efficient applications. A roadmap towards 7 nm will provide a path towards the next generation of high-performance, low-power semiconductor devices.
- **Leading-edge nodes below 2 nm:** This pilot line will focus on developing cutting-edge technology for advanced semiconductors at the size of 2 nanometres and below, which will play essential roles in a variety of applications, from computing to communication devices, transport systems and critical infrastructure.
- **Heterogeneous system integration and assembly:** Heterogeneous integration is an increasingly attractive technology for innovation and increased performance. It refers to the use of advanced packaging technologies and novel techniques to combine semiconductor materials, circuits or components into one compact system.

- **Wide Bandgap semiconductors:** The focus will be on materials that allow electronic devices to operate at much higher voltage, frequency and temperature than standard silicon-based devices. Wide bandgap and ultra-wide bandgap semiconductors are necessary to develop highly efficient power, lighter weight, lower costs and radio-frequency electronics.

The deadline for the calls for these pilot lines is in early March 2024. More information on the application process for these calls and the pilot lines to be deployed is [available here](#).

Background

A common European strategy for the semiconductor sector was first announced by Commission President Ursula **von der Leyen** in her [2021 State of the Union address](#). In February 2022, the [Commission proposed the European Chips Act](#). In April 2023 a [political agreement](#) was reached between the European Parliament and the EU Member States on the Chips Act. The [Chips Act entered into force](#) on 21 September 2023, and with it the Regulation on the [Chips Joint Undertaking \(JU\)](#) and the European Semiconductor Board.

For More Information

[European Chips Act](#)

[European Chips Act - Questions & Answers](#)

[European Chips Act: Online Factpage](#)

[European Chips Act: Factsheet](#)

[Commission proposal for a European Chips Act](#)

[A European Chips Act Communication](#)

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Quotes:

"I warmly welcome the launch of the Chips Joint Undertaking and the new pilot lines for semiconductors. We cannot achieve our Digital Decade without the foundational technologies on which our digital society is built. Our transition to a more digital future is dependent on our access to and leadership on semiconductors."
Věra Jourová, Vice-President for Values and Transparency - 30/11/2023

"With already 100 billion euros invested in European semiconductors, the EU Chips Act is fully in motion. Now with the launch of the Chips JU and pilot lines, we take a bold step forward to advance our semiconductor industry. In a world of supply chain disruptions and geopolitical tensions, Europe is taking its technological and industrial destiny in its own hands."
Thierry Breton, Commissioner for Internal Market - 30/11/2023

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